

Title (en)
INTERSPINOUS IMPLANTS AND METHODS

Title (de)
INTERSPINALE IMPLANTATE UND VERFAHREN DAFÜR

Title (fr)
IMPLANTS INTERÉPINEUX ET MÉTHODES ASSOCIÉES

Publication
EP 2464316 A2 20120620 (EN)

Application
EP 10808656 A 20100810

Priority

- US 23268009 P 20090810
- US 53871009 A 20090810
- US 2010045079 W 20100810

Abstract (en)
[origin: WO2011019756A2] The present invention provides spinous process implant and associated methods. In one aspect of the invention the implant limits the maximum spacing between the spinous processes. In another aspect of the invention, a spacer has at least one transverse opening to facilitate tissue in-growth. In another aspect of the invention, an implant includes a spacer and separate extensions engageable with the spacer. The spacer is provided in a variety of lengths and superior to inferior surface spacings. In another aspect of the invention, an implant includes a spacer and a cerclage element offset from the midline of the spacer in use so that the spacer defines a fulcrum and the cerclage element is operative to impart a moment to the vertebrae about the spacer. In another aspect of the invention, instrumentation for inserting the implant is provided. In other aspects of the invention, methods for treating spine disease are provided.

IPC 8 full level
A61F 2/44 (2006.01); **A61B 17/70** (2006.01); **A61B 17/82** (2006.01)

CPC (source: EP KR)
A61B 17/70 (2013.01 - KR); **A61B 17/7053** (2013.01 - EP); **A61B 17/7061** (2013.01 - EP); **A61B 17/7068** (2013.01 - EP);
A61B 17/82 (2013.01 - KR); **A61F 2/44** (2013.01 - KR)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)
WO 2011019756 A2 20110217; **WO 2011019756 A3 20110616**; AU 2010282590 A1 20120308; CN 102573706 A 20120711;
CN 102573706 B 20160316; EP 2464316 A2 20120620; EP 2464316 A4 20140806; JP 2013501582 A 20130117; KR 20120062764 A 20120614;
MX 2012001849 A 20120508

DOCDB simple family (application)
US 2010045079 W 20100810; AU 2010282590 A 20100810; CN 201080045586 A 20100810; EP 10808656 A 20100810;
JP 2012524792 A 20100810; KR 20127006401 A 20100810; MX 2012001849 A 20100810